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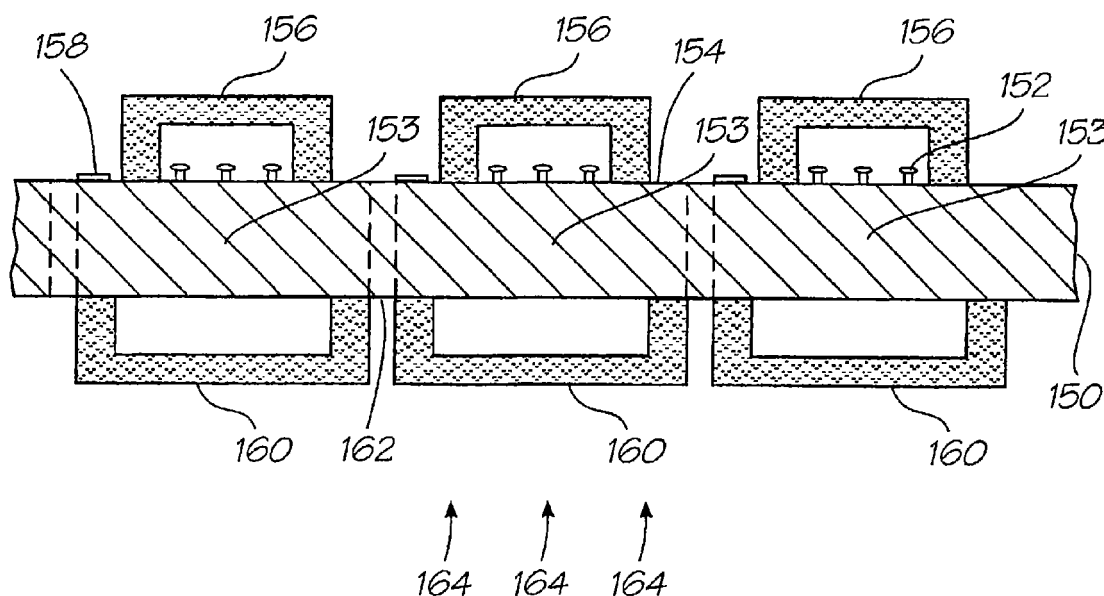
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(54) Title: INKJET DEVICE ENCAPSULATED AT THE WAFER SCALE



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(57) Abstract: Micro-fabricated devices (152) is packaged at the wafer (150) stage with a cap (156, 160) applied to one or both sides of the wafer (150) prior to separation of the wafer into separate devices. The cap (156) on the top side overlays the respective device(s) (152), except the bond pads (158). The cap (160) on the bottom overlays all of the respective device(s) (152).

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